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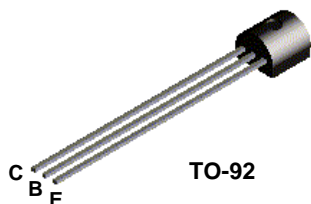
[PN2484](#)

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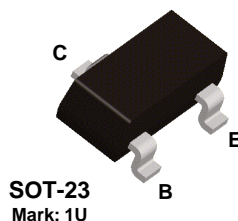
[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)



## PN2484



## MMBT2484



### NPN General Purpose Amplifier

This device is designed for low noise, high gain, general purpose amplifier applications at collector currents from 1μ to 50 mA. Sourced from Process 07. See 2N5088 for characteristics.

#### Absolute Maximum Ratings\*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	60	V
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
I <sub>C</sub>	Collector Current - Continuous	100	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

#### Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		PN2484	*MMBT2484	
P <sub>D</sub>	Total Device Dissipation	625	350	mW
	Derate above 25°C	5.0	2.8	mW/°C
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	83.3		°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	200	357	°C/W

\*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

**NPN General Purpose Amplifier**

(continued)

**Electrical Characteristics**

TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
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**OFF CHARACTERISTICS**

BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> = 10 μA, I <sub>B</sub> = 0	60		V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage*	I <sub>C</sub> = 10 mA, I <sub>E</sub> = 0	60		V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	I <sub>C</sub> = 10 μA, I <sub>E</sub> = 0	6.0		V
I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = 45 V, I <sub>E</sub> = 0		10	nA
		V <sub>CB</sub> = 45 V, I <sub>E</sub> = 0, T <sub>A</sub> = 150°C		10	μA
I <sub>EBO</sub>	Emitter Cutoff Current	V <sub>EB</sub> = 5.0 V, I <sub>C</sub> = 0		10	nA

**ON CHARACTERISTICS**

h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> = 1.0 μA, V <sub>CE</sub> = 5.0 V I <sub>C</sub> = 10 μA, V <sub>CE</sub> = 5.0 V I <sub>C</sub> = 100 μA, V <sub>CE</sub> = 5.0 V I <sub>C</sub> = 100 μA, V <sub>CE</sub> = 5.0 V T <sub>A</sub> = -55°C I <sub>C</sub> = 500 μA, V <sub>CE</sub> = 5.0 V I <sub>C</sub> = 1.0 mA, V <sub>CE</sub> = 5.0 V I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 5.0 V*	30 100 175 20 200 250	500	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 1.0 mA, I <sub>B</sub> = 0.1 mA		0.35	V
V <sub>BE(on)</sub>	Base-Emitter On Voltage	I <sub>C</sub> = 100 μA, V <sub>CE</sub> = 5.0 V	0.5	0.7	V

**SMALL SIGNAL CHARACTERISTICS**

C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 5.0 V, f = 140 kHz		6.0	pF
C <sub>ibo</sub>	Input Capacitance	V <sub>EB</sub> = 0.5 V, f = 140 kHz		6.0	pF
NF	Noise Figure	I <sub>C</sub> = 10 μA, V <sub>CE</sub> = 5.0 V, R <sub>S</sub> = 10k, f = 1.0 kHz, BW = 200 Hz		3.0	dB

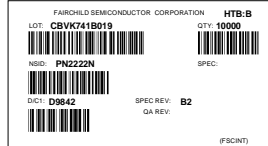
\*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 3.0%

## TO-92 Tape and Reel Data



### TO-92 Packaging Configuration: Figure 1.0

FSCINT Label sample

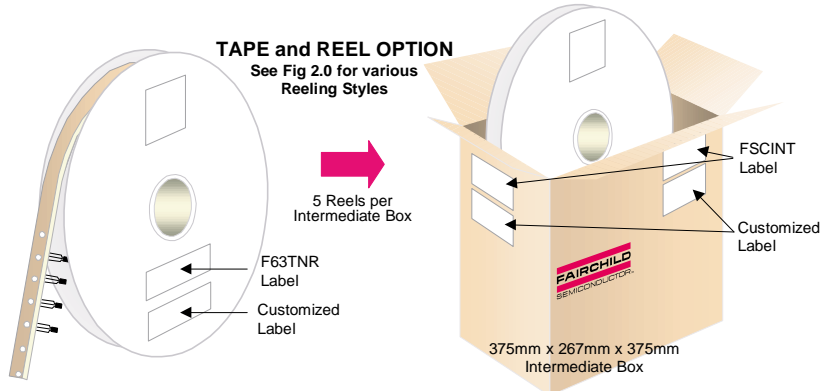


F63TNR Label sample



### TAPE and REEL OPTION

See Fig 2.0 for various Reeling Styles



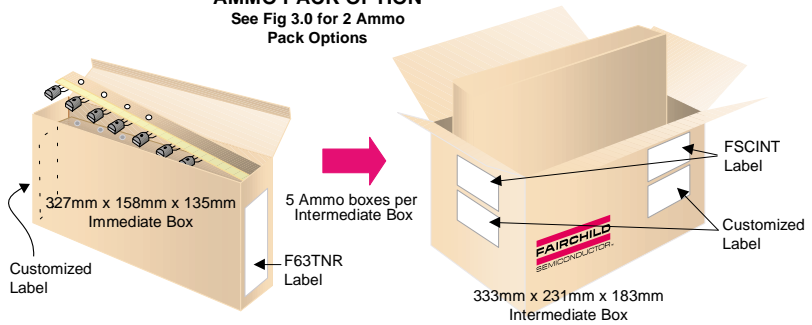
### TO-92 TNR/AMMO PACKING INFORMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm  
 Reel weight with components = 1.04 kg  
 Ammo weight with components = 1.02 kg  
 Max quantity per intermediate box = 10,000 units

### AMMO PACK OPTION

See Fig 3.0 for 2 Ammo Pack Options

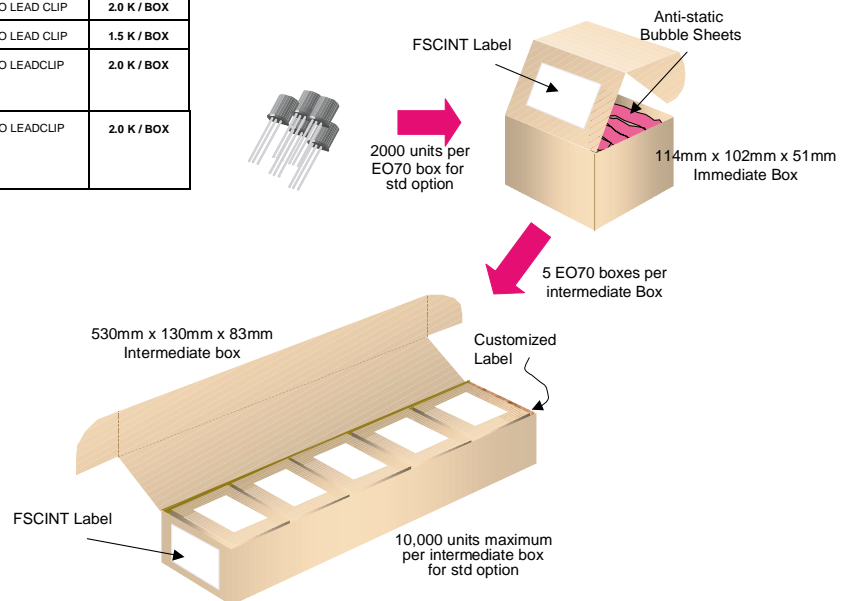


### (TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K / BOX
L34Z	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98	NO LEADCLIP	2.0 K / BOX

### BULK OPTION

See Bulk Packing Information table

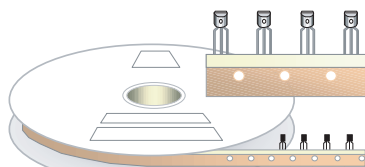


**TO-92 Tape and Reel Data and Package Dimensions, continued**

**TO-92 Reeling Style**

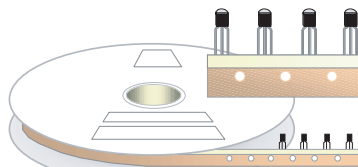
**Configuration: Figure 2.0**

**Machine Option "A" (H)**



**Style "A", D26Z, D70Z (s/h)**

**Machine Option "E" (J)**

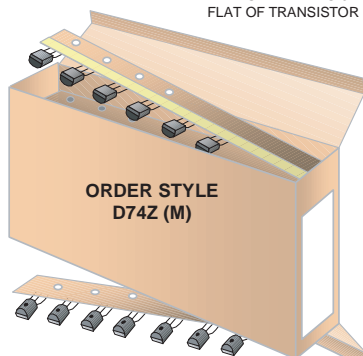


**Style "E", D27Z, D71Z (s/h)**

**TO-92 Radial Ammo Packaging**

**Configuration: Figure 3.0**

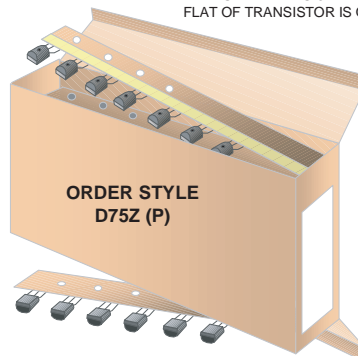
FIRST WIRE OFF IS COLLECTOR  
 ADHESIVE TAPE IS ON THE TOP SIDE  
 FLAT OF TRANSISTOR IS ON TOP



**ORDER STYLE  
 D74Z (M)**

FIRST WIRE OFF IS EMITTER (ON PKG. 92)  
 ADHESIVE TAPE IS ON BOTTOM SIDE  
 FLAT OF TRANSISTOR IS ON BOTTOM

FIRST WIRE OFF IS EMITTER  
 ADHESIVE TAPE IS ON THE TOP SIDE  
 FLAT OF TRANSISTOR IS ON BOTTOM



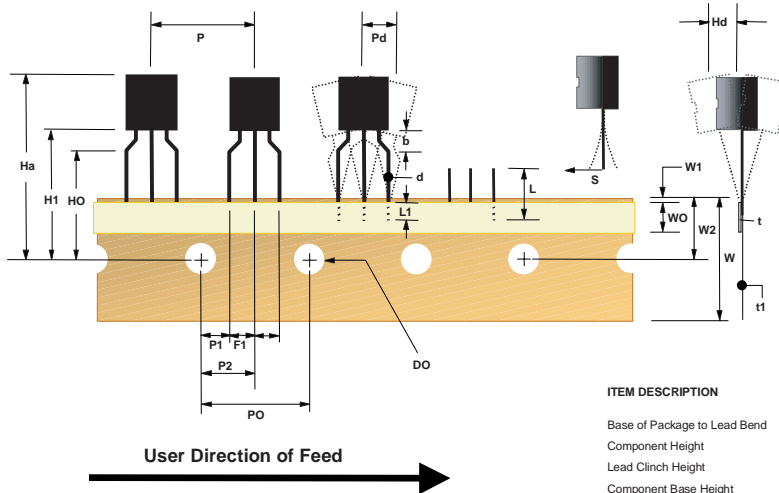
**ORDER STYLE  
 D75Z (P)**

FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)  
 ADHESIVE TAPE IS ON BOTTOM SIDE  
 FLAT OF TRANSISTOR IS ON TOP

## TO-92 Tape and Reel Data and Package Dimensions, continued

### TO-92 Tape and Reel Taping

Dimension Configuration: Figure 4.0

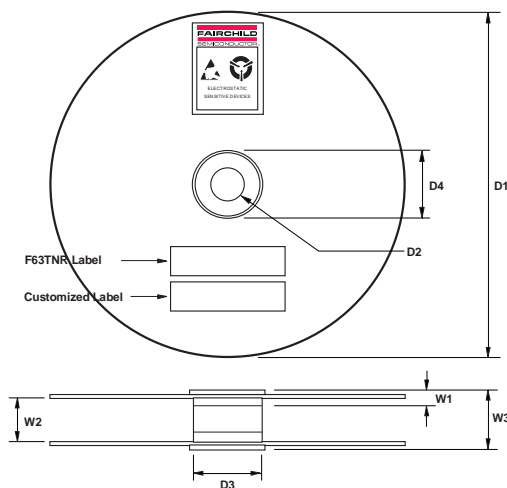


ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment ( side/side )	Pd	0.040 (max)
Component Alignment ( front/back )	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

### TO-92 Reel

Configuration: Figure 5.0

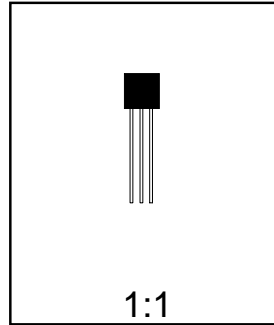
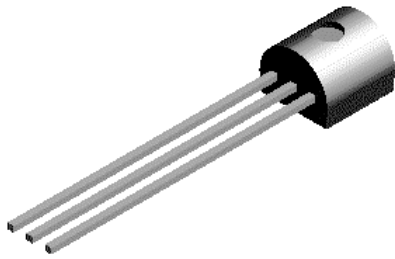


ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

**TO-92 Tape and Reel Data and Package Dimensions**

**TO-92 (FS PKG Code 92, 94, 96)**



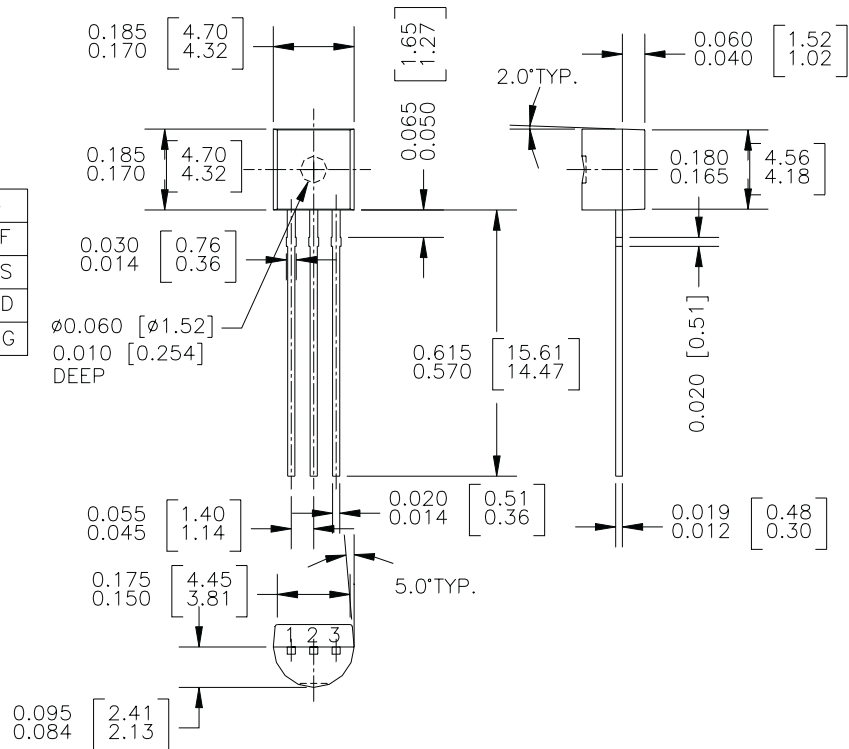
Scale 1:1 on letter size paper

Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO-92 (92,94,96)

PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G



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|---|---|

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